



DUAL-SIDE FLYING PROBE TESTER

APT-2600FD Series



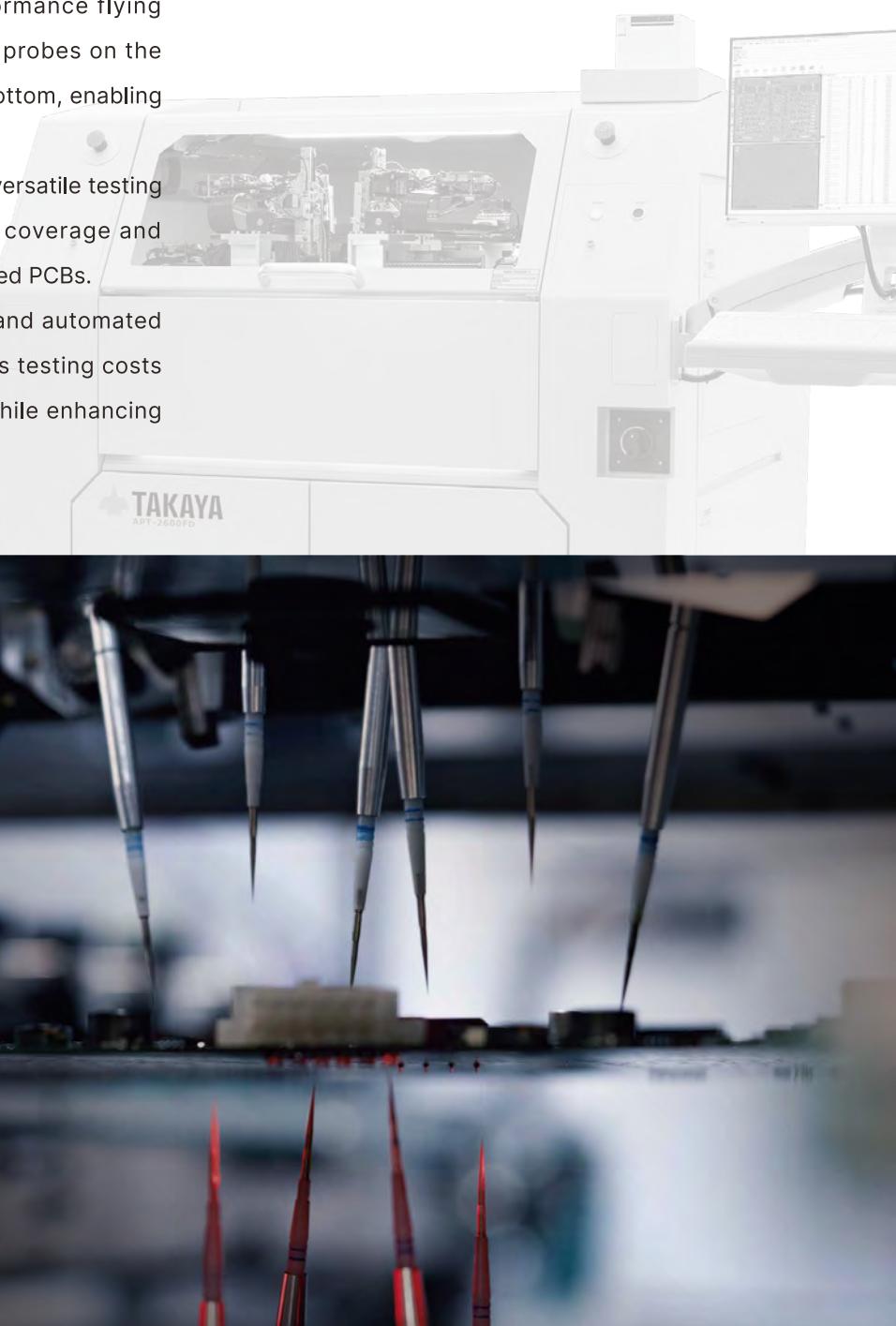
Ultrafast Speed & High Performance

Your Gateway to Quality.

The APT-2600F series is a high-performance flying probe test system with 4 heads and 6 probes on the top, and 2 heads and 4 probes on the bottom, enabling simultaneous double-sided contact.

Its advanced measurement system and versatile testing capabilities significantly improve test coverage and detect manufacturing defects in assembled PCBs.

Offering various models for large PCB and automated testing, the APT-2600FD series reduces testing costs from prototyping to mass production while enhancing assembly quality.



Point 01 Dual-Sided Flying Probe Testing

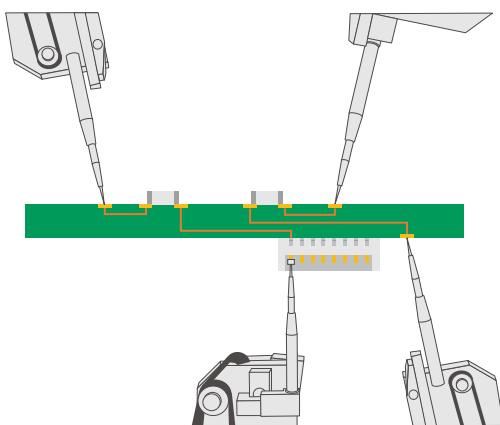
Point 02 Advanced Measurement System

Point 03 Zero-Impact Probe Control

APT-2600FD Series

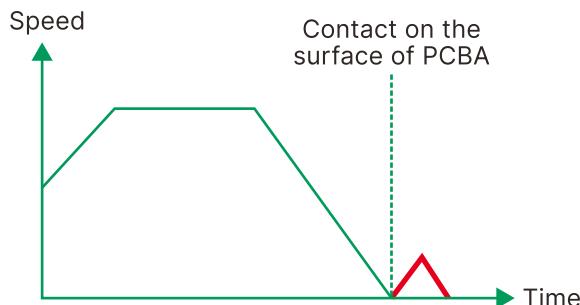
01 Dual-Sided Flying Probe Testing

Using up to 6 probes for simultaneous top and bottom testing, the system allows components requiring contact on both PCB surfaces to be tested. This improves test coverage, reduces the risk of damage from flipping the board, and shortens test time.



03 Zero-Impact Probe Control

To minimize impact, the system reduces probe speed to zero just before contact, using only spring pressure. This greatly reduces stress on contact points and lowers the risk of board damage, ensuring safe, accurate testing even for delicate PCBs.

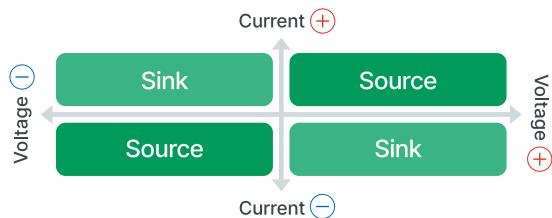


05 Temperature Sensor

The newly developed temperature sensor measures V-I curves to detect semiconductor failures and misassembled components that conventional in-circuit testing cannot. It also offers temperature compensation and non-contact measurement to prevent temperature drift, further improving test coverage.

02 Advanced Measurement System

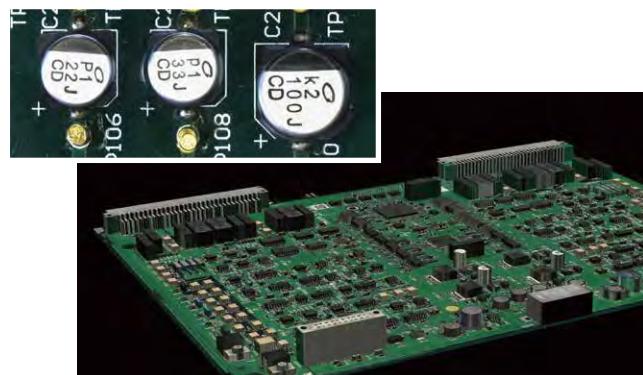
The APT-2600FD series features a 16-bit DC 4-quadrant source and an AC programmable generator, allowing it to apply optimal measurement signals based on component specifications and circuit conditions. This enables both in-circuit and functional testing, effectively detecting a wide range of assembly defects.



04 High-Resolution Vision System with Multi-Function

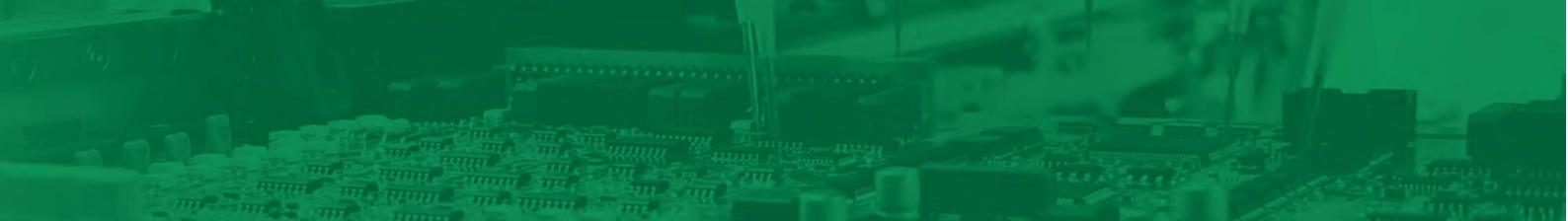
With a high-resolution camera and liquid lens technology, the system provides a wide depth of field, capturing clear images regardless of component height, making it easy to read markings on tall components.

In addition to high-performance OCR and AOI, the imaging has evolved from 2D to 3D real maps, enabling checking of hard-to-reach areas and net connections between the top and bottom of the PCB.



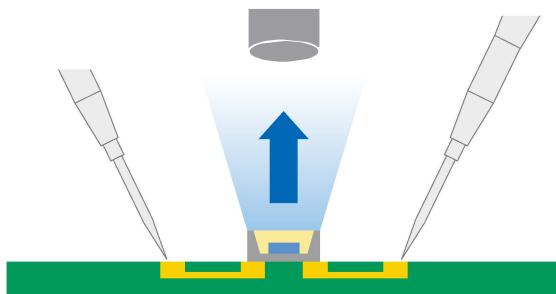
06 Distance Sensor

The distance sensor measures the height of the PCB surface and components, enabling detection of defects like lifted parts that are hard to spot with AOI or electrical tests. By accounting for board warping, the system automatically adjusts probe coordinates, ensuring accurate and stable contact regardless of board warpage.



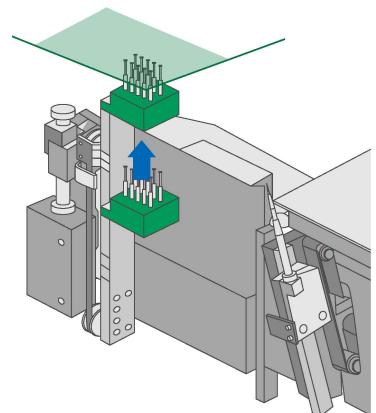
07 Flying LED Color Sensor

The flying LED color sensor detects differences in LED emission colors without dedicated fixtures. By quantifying hue, saturation, and luminance — difficult to distinguish visually — it ensures stable inspections with clear, precise criteria.



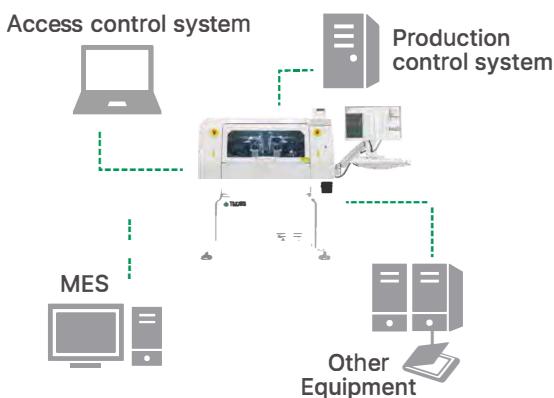
08 Multi-probe System

A dedicated mechanism in the movable axis unit for bottom-side flying probes enables simultaneous contact with multiple points on the bottom side of PCB. This enhances functionality by supporting integration with external devices like ISP (In-System Programming).



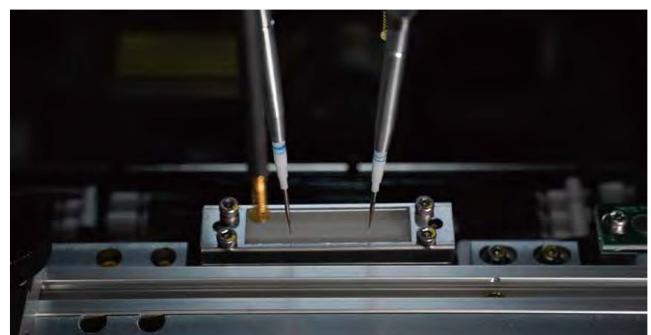
09 Industry 4.0 Ready

Multiple interfaces are available for seamless integration with your factory's network, enhancing QCD (Quality, Cost, Delivery) through quick traceability, inspection visualization, and rapid issue response.



10 Automatic Probe Cleaning for Reliable Testing

The system includes a probe cleaner that automatically removes flux and dust from the flying probe tips, with adjustable cleaning interval. This reduces false judgments and ensures stable, reliable inspections.



11 IC-OPEN System for Detecting IC Lead Solder Failures

The proprietary IC-OPEN test system detects IC lead solder failures in bus circuits, which are challenging to identify with standard QFP lead or BGA solder ball inspections.

Lineup

		Standard Size		Large Size			
Model		APT-2600FD	APT-2600FD-A	APT-2600FD-SL	APT-2600FD-SL-A		
							
In-line system		—	Support In-line	—	Support In-line		
Probes	Top	4 tilted contact probes, 2 vertical contact probes, 2 IC-open test probes					
	Bottom	2 tilted contact probes, 2 vertical contact probes or IC-open test probes					
Testable PCB	Size(L×W)	540mm(21") × 483mm(19")	540mm(21") × 483mm(19") 890mm(35") × 483mm(19")*1	635mm(25") × 610mm(24")	635mm(25") × 610mm(24") 985mm(38.7") × 610mm(24")*1		
		Thickness					
	Weight	5Kgs (11 lbs)		15Kgs (33 lbs)			
Component height	Top	60mm					
	Bottom*2	60mm					
Component-free area	Top	3mm					
	Bottom	3mm			7mm		
Test time*3	Single test	0.05~0.06sec. / step		0.07~0.08sec. / step			
	Combination test	0.02~0.03sec. / step		0.03~0.04sec. / step			
Positioning repeatability of flying probes(XY)*4		±25µm					
Minimum pad size for flying probe*4		50µm					
Minimum pad pitch for flying probe		150µm					

*1 Divided PCB test function required. *2 PCB thickness included.

*3 XY 2.5mm pitch movement. *4 In high precision mode with high accuracy needle probe used.

■ Automated Conveyor System

By connecting the flying probe tester with a loader/unloader, a continuous automated inline system with speeds of up to 40 m/min can be established. To meet diverse user needs, the system supports buffer stations equipped with conveyors to minimize transport time and communication interfaces compliant with the IPC-HERMES-9852 standard.



Specification

■ Electrical tests

In-Circuit Testing / Open & Short Testing / On-Test for Passive Components

Lead & BGA Soldering Defects Testing / NSW Testing / Functional Testing / Voltage & Current Measurement

Frequency Measurement / In-system Programming / Boundary Scan Testing / Leakage Current Measurement ...

■ Other tests

Optical Testing: Presence, misalignment, polarity, incorrect part, color differences, etc.

Laser Testing: Component height, presence, misalignment, PCB warping, etc.

Temperature Testing: Temperature monitoring, semiconductor failures, incorrect part

LED Color Testing: Hue, saturation, and luminance of LEDs

■ Option

LED color test system / DC ±80V/±1A programmable source & measure board unit / Function scanner board / Marking unit

Temperature sensor / Probe cleaner / Multi-probe system / Lateral illumination / Fast track...

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